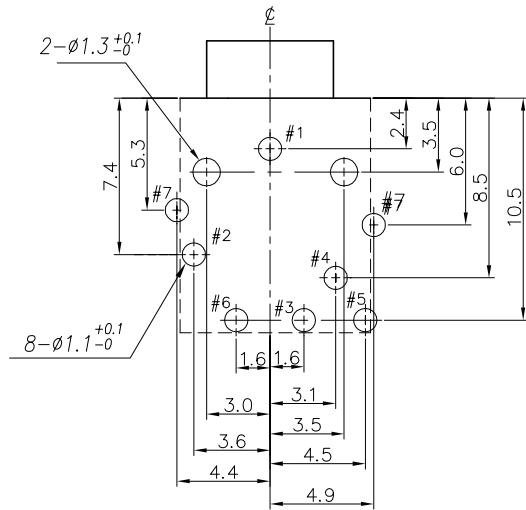
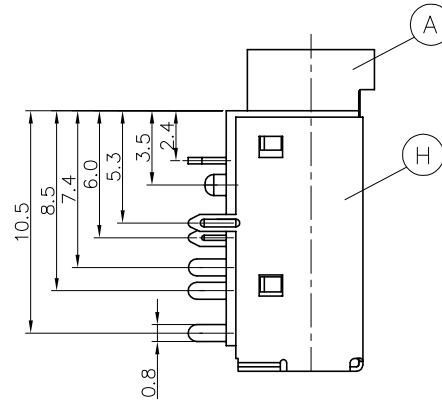
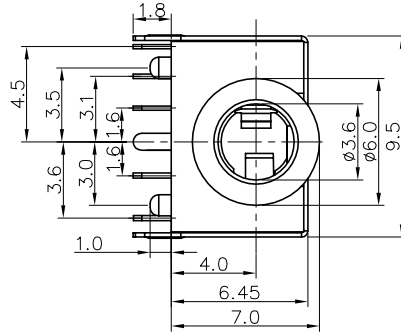
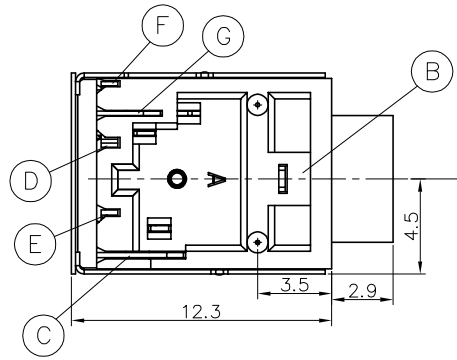
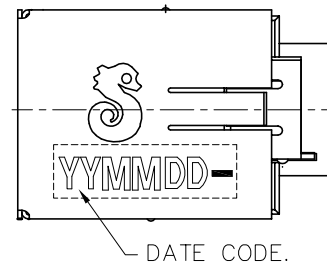
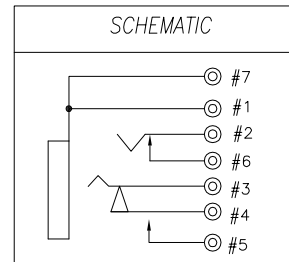
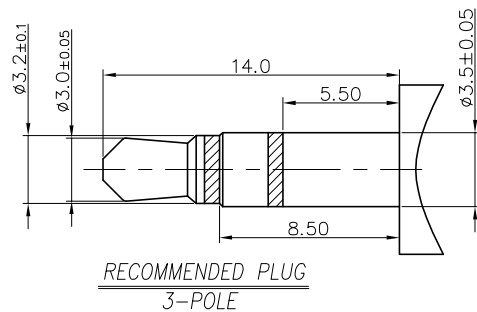


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: T131111-5A	MARS	2014.01.03



RECOMMENDED PCB LAYOUT
TOP VIEW (TOL.±0.05)



SPECIFICATIONS:

- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
- CONTACT RESISTANCE: 30mΩ MAX. (200mΩ MAX:METAL TO EARTH TO SHIELDING)
- INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
- LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
- INSERTION FORCE: 0.3 - 3Kg.
- WITHDRAWAL FORCE: 0.3 - 3Kg.
- AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
- AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
- MARKING: MARK "S" ON TOP OF CONNECTOR.
- PACKAGING : TRAY
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
- HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:
- FOR LEAD-FREE PROCESS.

H	SHIELDING	1	COPPER ALLOY 0.2t	Ni 60 u" Min
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	120u" Sn ON SOLDER
F	MAKE TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA ALL OVER 50u" Ni.
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
D	SHUNT TERMINAL-A	1	BRASS 0.25t	GOLD FLASH ON CONTACT AREA OVER 50u" Ni.
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag0.5 um Min, OVER 50u" Ni .
B	EARTH	1	COPPER ALLOY 0.3t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.3	X.X :±1°
X.XX :±0.2	

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5φ PHONE JACK			
DWN	MARS	PART NO. 2SJ-B351-S62F		
CHKD	BRUCE	SCALE: 4/1	UNIT: mm	
APVD	LUSSEN	SIZE: A3	SHEET: 1 OF 1	REV:A

CUSTOMER COPY